

**Amendments to the Specification:**

Please replace the paragraphs from page 4, line 9 to page 5, line 18, as follows:

To solve the above problems, an exposure method of the present invention is an exposure method that transfers a pattern on a mask-~~(R)~~ onto a substrate-~~(W)~~ using a catadioptric projection optical system-~~(PL)~~ that has a plurality of partial lens barrels-~~(4, 5)~~ having optical axes-~~(AX1—AX3)~~ that extend in mutually different directions. An amount of rotation of said catadioptric projection optical system about an optical axis-~~(AX3)~~ intersecting at least one of said mask and said substrate is measured, and at least one of the attitude and the scan direction of at least one of said mask and said substrate is adjusted based on the result of the measurement of said rotation amount.

In addition, an exposure method of the present invention is an exposure method that transfers the pattern on said mask onto said substrate while using a catadioptric projection optical system-~~(PL)~~ that has partial lens barrels-~~(4, 5)~~ having optical axes-~~(AX1—AX3)~~ that extend in mutually different directions to scan the mask-~~(R)~~ and the substrate-~~(W)~~. At least one of the attitude and the scan direction of at least one of said mask and said substrate is adjusted according to an amount of rotation of said catadioptric projection optical system about an optical axis-~~(AX3)~~ intersecting at least one of said mask and said substrate.

In addition, an exposure apparatus of the present invention is an exposure apparatus ~~(EX)~~ comprising a catadioptric projection optical system-~~(PL)~~ that has a plurality of partial lens barrels-~~(4, 5)~~ having optical axes-~~(AX1—AX3)~~ that extend in mutually different directions, a mask stage-~~(9)~~ that holds a mask-~~(R)~~, and a substrate stage-~~(16)~~ that holds a substrate-~~(W)~~ and that transfers the pattern on said mask onto said substrate via said catadioptric projection optical system. The apparatus comprises a measuring device-~~(25—28, 40a—42a, 40b—42b, 43a—43e and 44a—44e)~~, which measures an amount of rotation of

said catadioptric projection optical system about an optical axis ~~(AX3)~~ that intersects at least one of said mask and said substrate, and a control device ~~(30)~~, which adjusts at least one of the attitude and the scan direction of at least one of said mask stage and said substrate stage based on said rotation amount measurement results.

Through these inventions, exposure to the substrate is performed after having adjusted at least one of the attitude and the scan direction of at least one of the mask and the substrate according to the amount of rotation of the catadioptric projection optical system about an optical axis that intersects at least one of the mask and the substrate.

A device manufacturing method of the present invention is characterized in that it includes an exposure step ~~(S26)~~ that performs exposure processing on a substrate using the aforementioned exposure method or exposure apparatus and a development step ~~(S27)~~ that performs development of the substrate that has gone through said exposure process.